SAMSUNG DISPLAY

Customer: Sony DATE: 19.December.2012

SAMSUNG TFT-LCD

MODEL: LSY320AN02-A

(LCD Panel + Driver Ass'y O/C)

The Information described in this specification is for the first draft and can be changed without prior notice

Samsung Display Co., LTD

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The revision history

Date	Rev. No	Page	Summary
4. Sep. 2012	000	all	First Issue (First Draft)
14.Sep. 2012	001	6~8Page 30Page	Luminance , CR, Response Time Spec Revision Light source Revision(LTY320AN05-A BLU) Source PCB Top View Revision
12.Oct.2012	002	6Page 9Page 11Page 12 Page 32Page 33~35P	Optical Characteristics revision Note (9) Update Block Diagram revision Note (2) Update FFC Cable Update Appendix (2) Update
19.Oct.2012	003	36P~37P 38P~41P 42P~43P	Appendix 3 Update Appendix 4 Update Appendix 5 Update
5.Dec.2012	004	6Page 19Page 19Page 39Page 44Page	Optical characteristics revision The sequence of power on and off revision Spread spectrum specification update Panel Kit Packing revision Caution Update
19.Dec.2012	005	4Page 9Page	Note revision. Transmissivity Uniformity Update.

General Description

Description

This model uses a liquid crystal display (LCD) of amorphous silicon TFT as switching components. This model is composed of a TFT LCD panel, a driver circuit, and an ass'y KIT of source PBA. This 32.0" model has a resolution of a 1366*768(16:9) and can display up to 16.7 million colors with the wide viewing angle of 89° or a higher degree in all directions. This panel is designed to support applications by providing a excellent performance function of the flat panel display such as home-alone multimedia TFT-LCD TV and a high definition TV.

General Information

Features

- RoHS compliance (Pb-free)
- High contrast ratio & aperture ratio with the wide color gamut
- SVA(Super vertical align) mode
- Wide viewing angle (±178°)
- High speed response
- HD resolution (16:9)
- Low power consumption
- DE (Data enable) mode
- The interface (1pixel/clock) of 2ch LVDS (Low voltage differential signaling)

Items	Specification	Unit	Note
Active Display Area	697.6845 (H) ×392.256 (V)	㎜	
Switching Components	a-Si TFT Active matrix		
Glass Size	TFT : : 713.0000(H) X 410.500(V) CF : 713.0000(H) X 408.200(V)	mm	
Panel Size	713.0000(H) X 410.500(V)	mm	
	1.80(D)	mm	
Weight	1200	g	± 10%
Display Colors	16.7M (8bits True Display)	color	
Number of Pixels	1366 X 768	pixel	16 : 9
Pixel Arrangement	RGB Horizontal Stripe		
Display Mode	Normally Black		
Surface Treatment	Anti -Glare		
Haze	2.3%		± 2.1%
Hardness	2H		

1. Absolute Maximum Ratings

If the figures on measuring instruments exceed maximum ratings, it can cause the malfunction or the unrecoverable damage on the device.

Item	Symbol	Min.	Max.	Unit	Note
Power supply voltage	V_{DD}	11	13	V	(1)
Temperature for storage (Temperature of glass surface)	T_{STG}	-20	65	℃	(2),(4)
Operating temperature	T_{OPR}	0	50	℃	(2),(5)
Humidity for storage	H_{STG}	5	90	%RH	(2),(4)
Operating humidity	H_{STG}	20	90	%RG	(2),(5)
Endurance on static electricity			150	V	(3)

Note (1) The power supply voltage at Ta= 25 ± 2 °C

(2) Temperature and the range of relative humidity are shown in the figure below.

a. 90 % RH Max. (Ta ≤ 39 °C)

b. The relative humidity is 90% or less. (Ta > 39 °C)

c. No condensation

(3) Keep the static electricity under 150V in Polarizer attaching process.

(4) Operating condition with source PCB

(5) Storage temperature condition including glass

(6) Condition without packing. (Unpacking condition)

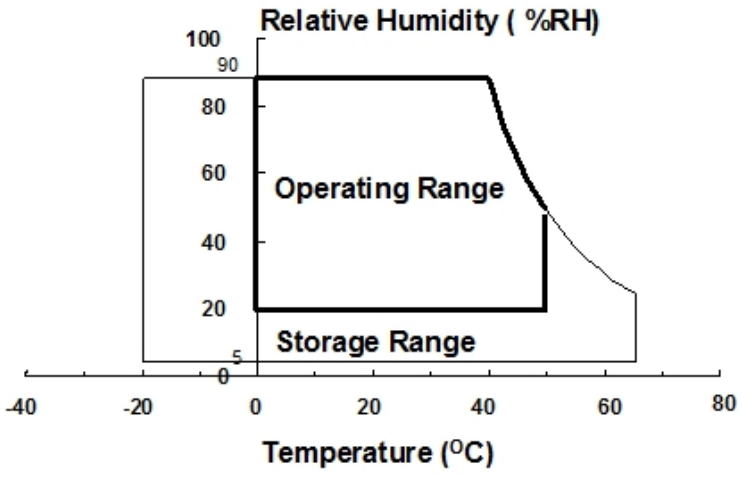


Fig. Range for temperature and relative humidity

2. Optical characteristics

The optical characteristics should be measured in the dark room or the space surrounded by the similar setting.

Measuring equipment : TOPCON RD-80S, TOPCON SR-3 ,ELDIM EZ-Contrast,

(Ta = 25 ± 2°C, VDD=12.0V, fv=60Hz, f_{DCLK}=148.5MHz, Light source: SONY BLU (LTY320AN05-A BLU)

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Light Source	Note
Contrast Ratio (At the Center of screen)		C/R*		3000	5000	-		Sony BLU (LTY320AN05)	(1) SR-3
Response time	G-to-G [AVE]	Tg	$T_{PAN,SUR}$ =25°C	-	20	30	msec	Sony BLU (LTY320AN05)	(3) RD-80S
Luminance of White (At the Center of screen)		Y_L	Normal qL,R=0 qU,D=0 Viewing Angle	330	400	-	cd/㎡	Sony BLU (LTY320AN05)	(4) SR-3
Transmissivity (At the center of screen)		Tr		5.7	6.4		%	D65 Standard light source	(7)
Color Chromaticity (CIE 1931)	Red	Rx		TYP. -0.03	0.645	TYP. +0.03		Sony BLU (LTY320AN05) Or Simulation with Sony BLU Spectrum	(5),(6),(9) SR-3 (Appendix2)
		Ry			0.329				
	Green	Gx			0.299				
		Gy			0.622				
	Blue	Bx			0.156				
		By			0.051				
	White	Wx			0.272				
		Wy			0.282				
Color Gamut		-		-	76	-	%		(5) SR-3
Color Temperature		-		-	10000	-	K		
Viewing Angle	Hor.	q_L	C/R≥10	79	89	-	Degree	Sony BLU (LTY320AN05)	(6) SR-3 EZ-Contrast
		q_R		79	89	-			
	Ver.	q_U		79	89	-			
		q_D		79	89	-			
Transmissivity Uniformity (9 Points)		T_{uni}				20	%	D65 Standard light source	(10)
Brightness Uniformity (9 Points)		B_{uni}		-	-	30	%	Sony BLU (LTY320AN05)	(2) SR-3
2Point Gamma		γ	7G ~ 57G (Full = 64G)	1.7	2.2	2.7		Sony BLU (LTY320AN05)	(8) SR-3

Notice

(a) Setup for test equipment

The measurement should be executed in a stable, windless, and dark room for 40min and 60min after operating the panel at the given temperature for stabilization of the standard light. (SDC uses the standard luminance of the LTY320AN05-A BLU).

This measurement should be measured at the center of screen.

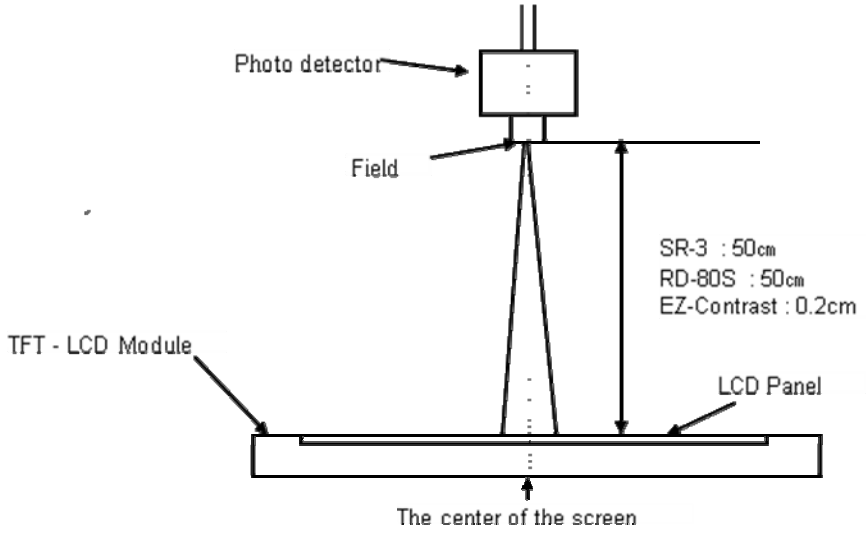
The environment condition: Ta = 25 ± 2 °C

(b) LTY320AN05-A BLU is consist of three diffuser sheets and LED light source.

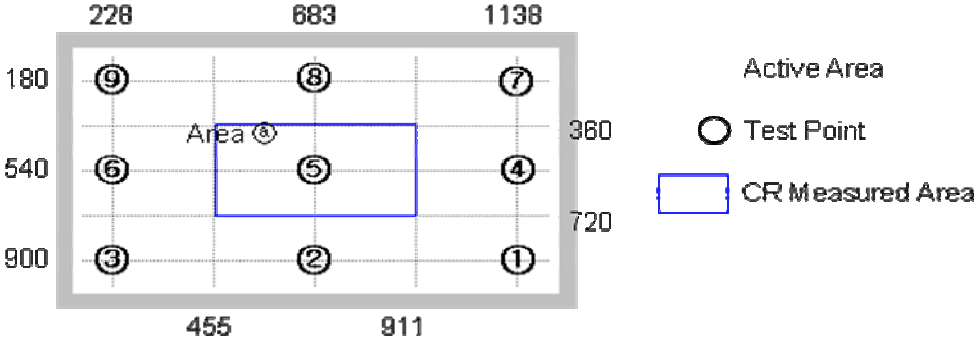
(c) D65 Standard Light Source.

The temperature of color is 6487K. The coordinate of color is Wx 0.313, Wy 0.329. The luminance of this product is 7217.3cd/m2

Photo detector	Field
SR-3	2°/1°
RD-80S	1°



- Definition of the test point



Note (1) Definition of contrast ratio (C/R)

: The ratio of gray max (Gmax) & gray min (Gmin) at the center point ⑤ of the panel

The measurement goes in LTY320AN05-A BLU

$$C/R = \frac{G\max}{G\min}$$

Gmax : The luminance with all white pixels

Gmin : The luminance with all black pixels

Note (2) Definition of the Brightness uniformity of 9 points (Test pattern : The full white)

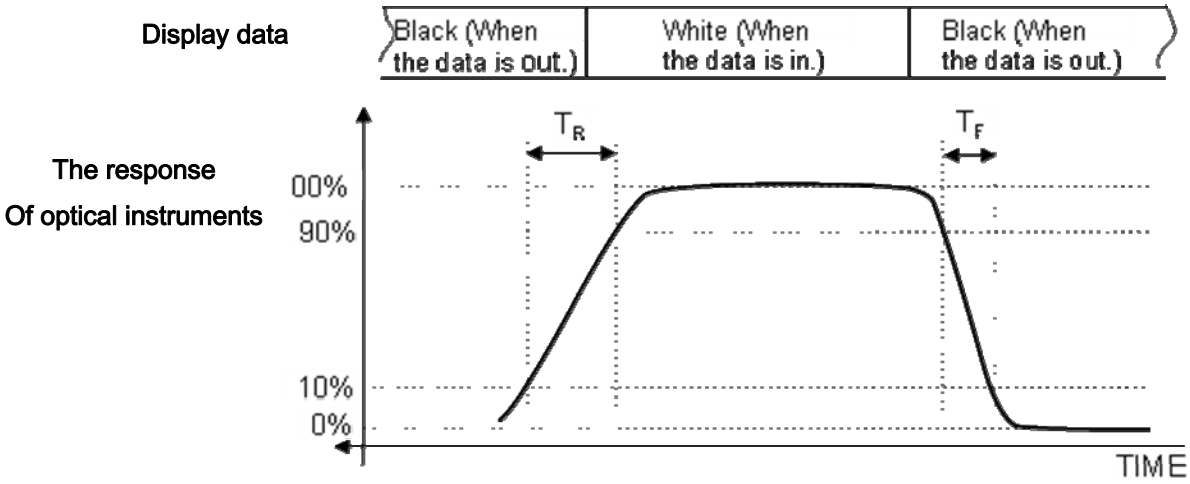
The measurement shall be executed with the LTY320AN05-A BLU

$$Buni = 100 * \frac{(B\max - B\min)}{B\max}$$

Bmax : The maximum brightness

Bmin : The minimum brightness

Note (3) Definition of the response time : Sum of Tr, Tf

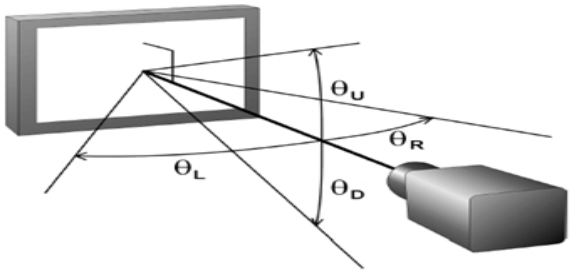


※ G-to-G : Average response time between whole gray scale to whole gray scale.
The response time is the value that was measured after it was operated in LTY320AN05-A BLU for one hour.(at room temperature)

Note (4) The definition of luminance of white: The luminance of white at the center point ⑤
The measurement shall be executed with the LTY320AN05-A BLU.

Note (5) The definition of chromaticity (CIE 1931)
The color coordinate of red, green, blue and white at the center point ⑤
The measurement shall be executed with the LTY320AN05-A BLU.

Note (6) Definition of viewing angle
: The range of viewing angle (C/R ≥10)
The measurement shall be executed with the LTY320AN05-A BLU.



Note (7) Definition of transmissivity
: The measurement shall be executed with the D65 Standard Light Source

Note (8) Definition of Gamma

$$Gamma = \log(X_{lum}/100)/\log(Y/100)$$

$$X_{lum} = (Z - B_{\min})/(B_{\max} - B_{\min}) \times 100$$

Y: Measurement Level / Z: Measurement Brightness

B_{max}: Maximum Brightness / B_{min}: Minimum Brightness

Note (9) Definition of Simulation with BLU Spectrum

Simulated color Chromaticity

$$\text{Color x} = \frac{Xsim}{Xsim + Ysim + Zsim} \quad , \text{Color y} = \frac{Ysim}{Xsim + Ysim + Zsim}$$

Xsim = Simulated Spectrum X CIE Color Matching Function x

Ysim = Simulated Spectrum X CIE Color Matching Function y

Zsim = Simulated Spectrum X CIE Color Matching Function z

Simulated Spectrum = Panel Transmittance Spectrum X Standard BLU Spectrum(Appendix2)

Note (10) Definition of the Transmissivity uniformity of 9 points

The measurement shall be executed with the D65 Standard Light Source

$$T_{uni} = 100 * \frac{(T_{max} - T_{min})}{T_{max}}$$

Tmax : The maximum transmissivity

Tmin : The minimum transmissivity

3. Electrical characteristics

3.1 TFT LCD Module

The connector for the display data & timing signal should be connected.

Ta = 25°C ± 2 °C

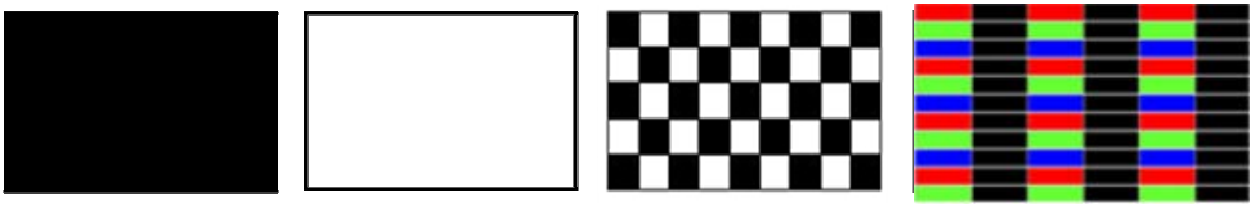
Item		Symbol	Min.	Typ.	Max.	Unit	Note
Voltage of Power Supply		V_{DD}	11	12	13	V	(1)
Current of Power Supply	(a) Black	I_{DD}	-	325	-	mA	(2),(3)
	(b) White		-	340	440		
	(c) Mosaic		-	335	-		
	(4) Max Pattern (V-stripe)		-	650	750		
Vsync Frequency		f_V	47	60	63	Hz	
Hsync Frequency		f_H	45	48.6	53	kHz	
Main Frequency		f_{DCLK}	65	80	86	MHz	
Rush Current		I_{RUSH}	-	-	3	A	(4)

Note (1) The ripple voltage should be controlled fewer than 10% of V_{DD} (Typ.) voltage.

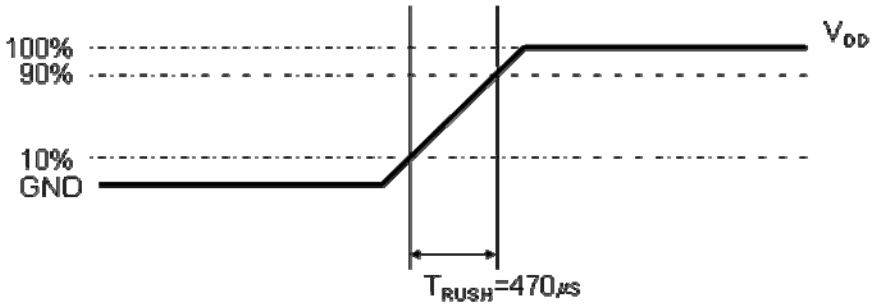
(2) fV=60Hz, fDCLK =80MHz, V_{DD} = 12.0V, DC Current.

(3) Power dissipation check pattern (LCD Module only)

a) Black pattern b) White pattern c) Mosaic d) Max Pattern(V-Stripe)

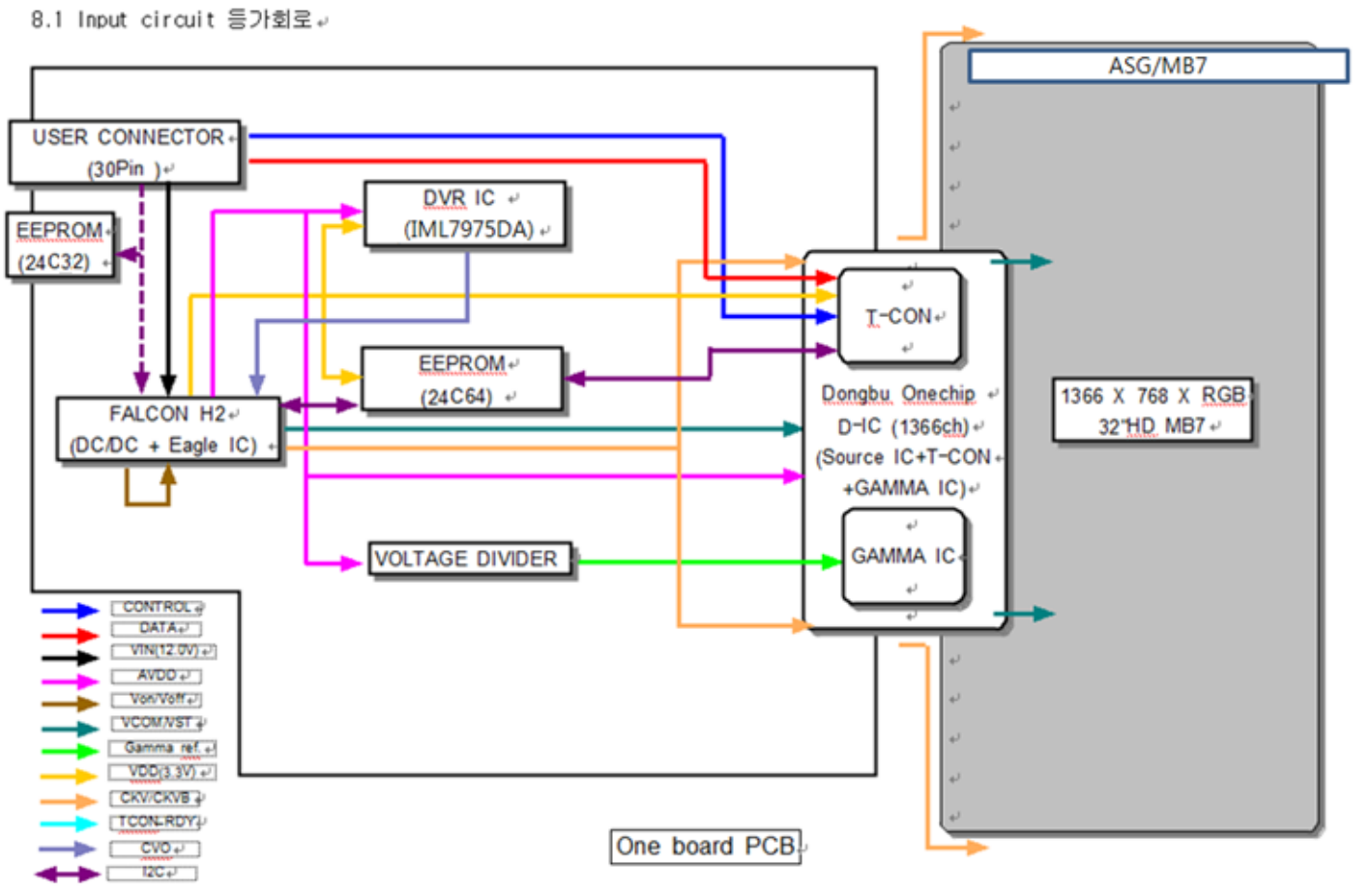


(4) Conditions for measurement



The rush current, I_{RUSH} can be measured during T_{RUSH} is 470us

4. Block diagram



5. The Pin assignment in the input terminal

5.1. Input signal & power

Connector : 196260-30041 (P-TWO Industries)

Pin	Symbol	Description	Pin	Symbol	Description
1	NC	NOTE1	16	GND	Ground
2	SCL_I	I2C SCL	17	LV3_NI	LV3_NI
3	SDA_I	I2C SDA	18	LV3_PI	LV3_PI
4	GND	Ground	19	GND	Ground
5	LV0_NI	LV0_NI	20	NC	NOTE1
6	LV0_PI	LV0_PI	21	LVDS_SEL	LVDS_SEL
7	GND	Ground	22	WPN(B_INT)	WPN(B_INT)
8	LV1_NI	LV1_NI	23	GND	Ground
9	LV1_PI	LV1_PI	24	GND	Ground
10	GND	Ground	25	NC	NOTE1
11	LV2_NI	LV2_NI	26	VDD	Vdd
12	LV2_PI	LV2_PI	27	VDD	Vdd
13	GND	Ground +	28	VDD	Vdd
14	LVCLK_NI	LVCLK_NI	29	VDD	Vdd
15	LVCLK_PI	LVCLK_PI	30	VDD	Vdd

Note (1) No connection: These PINS are used only for the product of SAMSUNG.

(DO NOT CONNECT the input device to these pins.)

■ Option Pin Description

These pins are CMOS interface.

Please use within the range of the following restriction.

VIH : 2.4V(min) / 3.5V(max)

VIL : 0.0V(min) / 0.4V(max))

■SCL : Pull up 22Ω/ 4.7kΩ

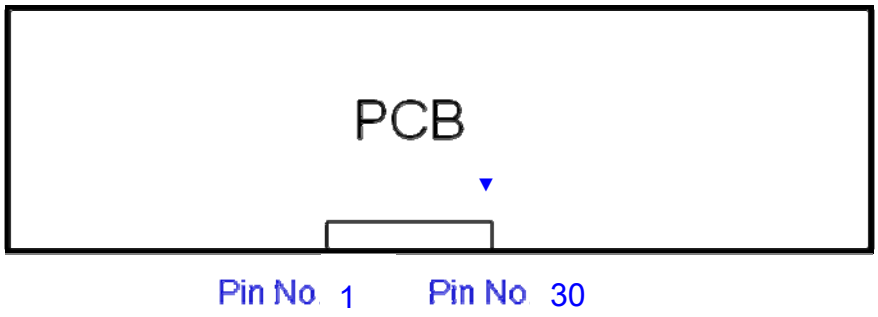
■SDA : Pull up 22Ω/ 4.7kΩ

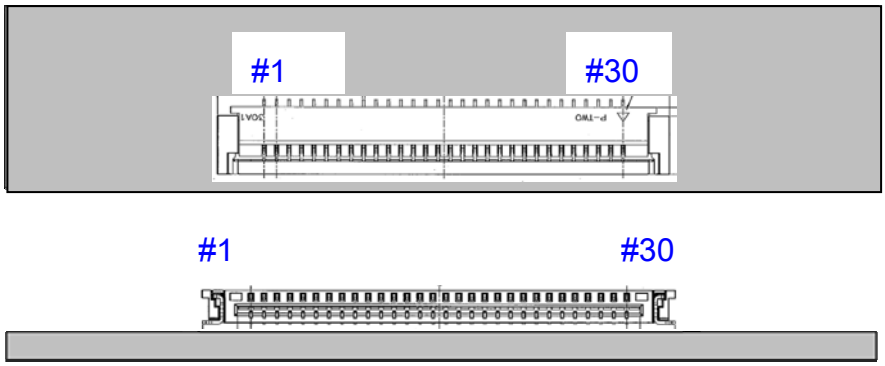
■LVDS_SEL : Pull up - Normal(VESA)

Pull down – JEIDA

Note (2) WPN,SCL_I and SDA_I shouldn't be communicated with I2C device whose output level is 5V

Note (3) Pin number which starts from the left side.





a. Power GND pins should be connected to the LCD's metal chassis.

b. All power input pins should be connected together.

c. All NC pins should be separated from other signal or power.

Note(4) LVDS OPTION : IF THIS PIN : LOW (GND V)/ NC → JEIDA LVDS FORMAT

OTHERWISE : HIGH (3.3V) → NORMAL NS LVDS FORMAT

5.2 LVDS Interface

- LVDS receiver : T-con (merged) (8Bit)
- Data format

	LVDS pin	JEIDA -DATA	Normal-DATA
TxOUT/RxIN0	TxIN/RxOUT0	R2	R0
	TxIN/RxOUT1	R3	R1
	TxIN/RxOUT2	R4	R2
	TxIN/RxOUT3	R5	R3
	TxIN/RxOUT4	R6	R4
	TxIN/RxOUT6	R7	R5
	TxIN/RxOUT7	G2	G0
TxOUT/RxIN1	TxIN/RxOUT8	G3	G1
	TxIN/RxOUT9	G4	G2
	TxIN/RxOUT12	G5	G3
	TxIN/RxOUT13	G6	G4
	TxIN/RxOUT14	G7	G5
	TxIN/RxOUT15	B2	B0
	TxIN/RxOUT18	B3	B1
TxOUT/RxIN2	TxIN/RxOUT19	B4	B2
	TxIN/RxOUT20	B5	B3
	TxIN/RxOUT21	B6	B4
	TxIN/RxOUT22	B7	B5
	TxIN/RxOUT24	HSYNC	HSYNC
	TxIN/RxOUT25	VSYNC	VSYNC
	TxIN/RxOUT26	DEN	DE
TxOUT/RxIN3	TxIN/RxOUT27	R0	R6
	TxIN/RxOUT5	R1	R7
	TxIN/RxOUT10	G0	G6
	TxIN/RxOUT11	G1	G7
	TxIN/RxOUT16	B0	B6
	TxIN/RxOUT17	B1	B7
	TxIN/RxOUT23	RESERVED	RESERVED

5.3 Input signals, basic display colors and the gray scale of each color. (8bit))

COLOR	DISPLAY (8bit)	DATA SIGNAL																								GRAY SCALE LEVEL
		RED								GREEN								BLUE								
		R0	R1	R2	R3	R4	R5	R6	R7	G0	G1	G2	G3	G4	G5	G6	G7	B0	B1	B2	B3	B4	B5	B6	B7	
BASIC COLOR	BLACK	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	-
	BLUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	-
	GREEN	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	-
	CYAN	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	-
	RED	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	-
	MAGENTA	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	-
	YELLOW	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	-
	WHITE	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	-
GRAY SCALE OF RED	BLACK	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	R0
	DARK ↑	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	R1
		0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	R2
		:	:	:	:	:	:			:	:	:	:	:	:			:	:	:	:	:	:			R3~ R252
	↓ LIGHT	:	:	:	:	:	:			:	:	:	:	:	:			:	:	:	:	:	:			
		1	0	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	R253
		0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	R254
	RED	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	R255
GRAY SCALE OF GREEN	BLACK	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	G0
	DARK ↑	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	G1
		0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	G2
		:	:	:	:	:	:			:	:	:	:	:	:			:	:	:	:	:	:			G3~ G252
	↓ LIGHT	:	:	:	:	:	:			:	:	:	:	:	:			:	:	:	:	:	:			
		0	0	0	0	0	0	0	0	1	0	1	1	1	1	1	1	0	0	0	0	0	0	0	0	G253
		0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	G254
	GREEN	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	G255
GRAY SCALE OF BLUE	BLACK	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	B0
	DARK ↑	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	B1
		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	B2
		:	:	:	:	:	:			:	:	:	:	:	:			:	:	:	:	:	:			B3~ B252
	↓ LIGHT	:	:	:	:	:	:			:	:	:	:	:	:			:	:	:	:	:	:			
		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	1	1	1	1	1	1	B253
		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	B254
	BLUE	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	B255

Note) The definition of gray :

Rn : Red gray, Gn : Green gray, Bn : Blue gray (n = Gray level)

Input signal : 0 = Low level voltage, 1 = High level voltage

6. Interface timing

6.1 The parameters of timing (Only DE mode)

SIGNAL	ITEM	SMBOL	MIN.	TYP.	MAX.	Unit	NOTE
Clock	Frequency	$1/T_C$	65	80	86	MHz	-
Hsync		F_H	45	48.6	53	KHz	-
Vsync		F_V	47	60	63	Hz	-
Term for the vertical display	Active display period	T_{VD}	-	768	-	Lines	-
	Total vertical	T_V	775	810	1300	Lines	-
Term for the horizontal display	Active display period	T_{HD}	-	1366	-	Clocks	-
	Total Horizontal	T_H	1450	1648	2000	clocks	-

Note) These products don't have to receive the signal of Hsync & Vsync from the input device.

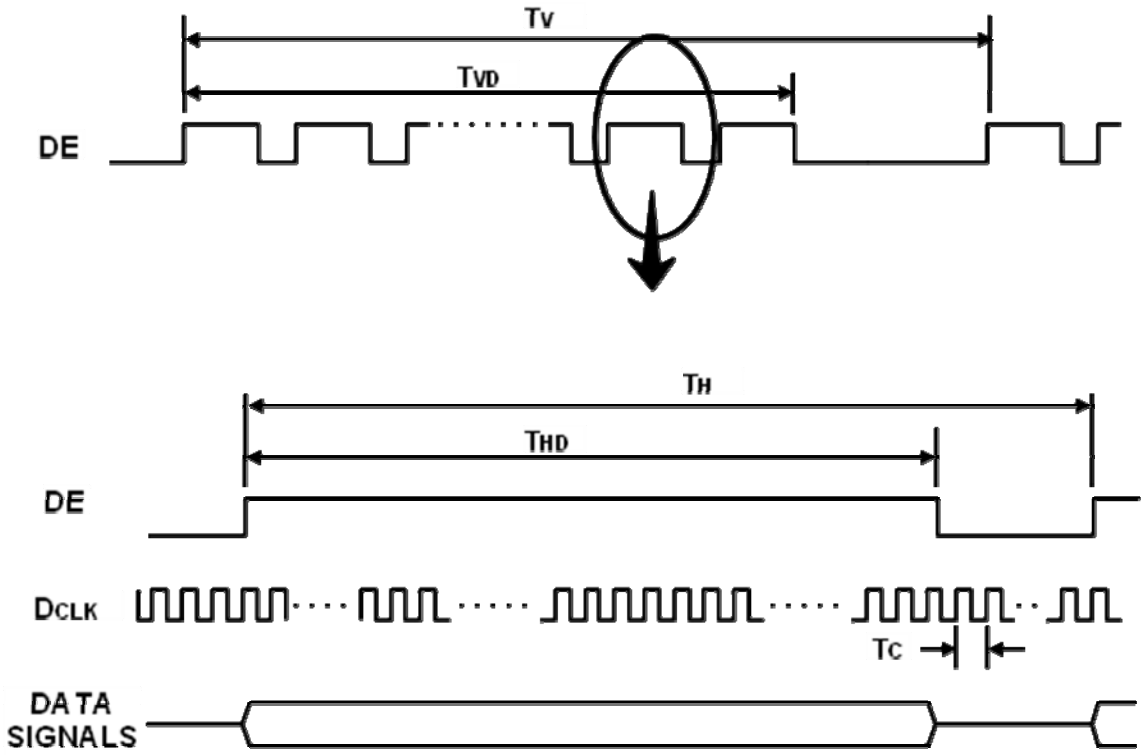
(1) Key points when testing: TTL controls the signal and the CLK at the input terminal of LVDS Tx of the system.

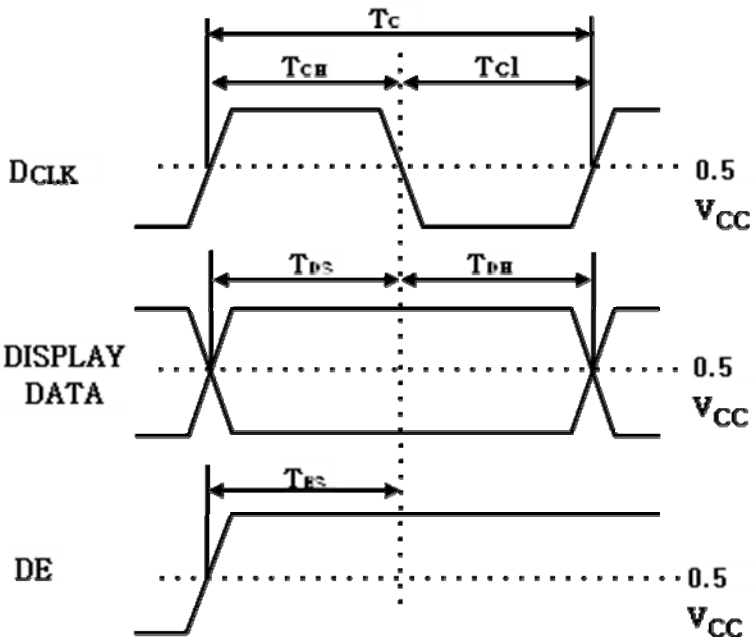
(2) Internal VDD = 3.3V

(3) Spread spectrum

- The limit of spread spectrum's range of SET in which the LCD module is assembled should be within ± 3 %.

6.2 Timing diagrams of interface signal (Only DE mode)





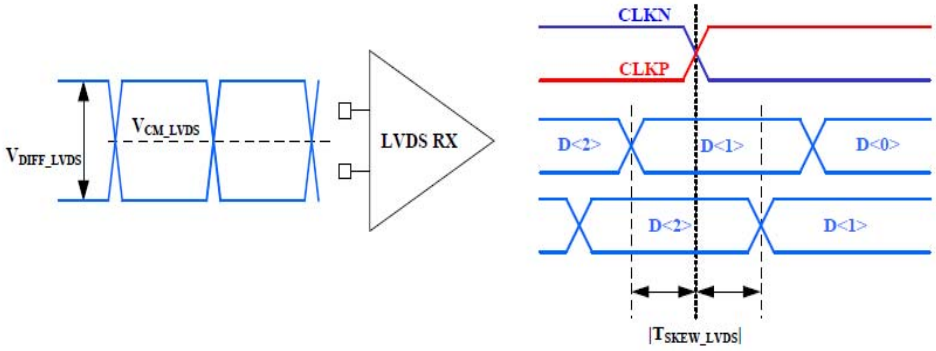
6.3 Characteristics of Input data of LVDS

(1) DC Specification

Symbol	Parameter	Condition		Min	Typ	Max	Unit
V_{DIFF_LVDS}	LVDS differential input	V_{CM_LVDS}=1.2V		100		600	mV
V_{CM_LVDS}	Input common level			VSSL +0.6	1.2	VDDL-0.6	V
I_{DD_LVDS}	Dynamic current consumption	V_{CM_LVDS} = 1.2V V_{DIFF_LVDS} = 200mV F_{CLK} = 85MHz	Within One LOT	-10%	13	+10%	mA
			Within Total LOT	-20%	13	+20%	
I_{DS_LVDS}	Static current consumption		Within One LOT	-10%	13	+10%	
			Within Total LOT	-20%	13	+20%	

(2) AC Specification

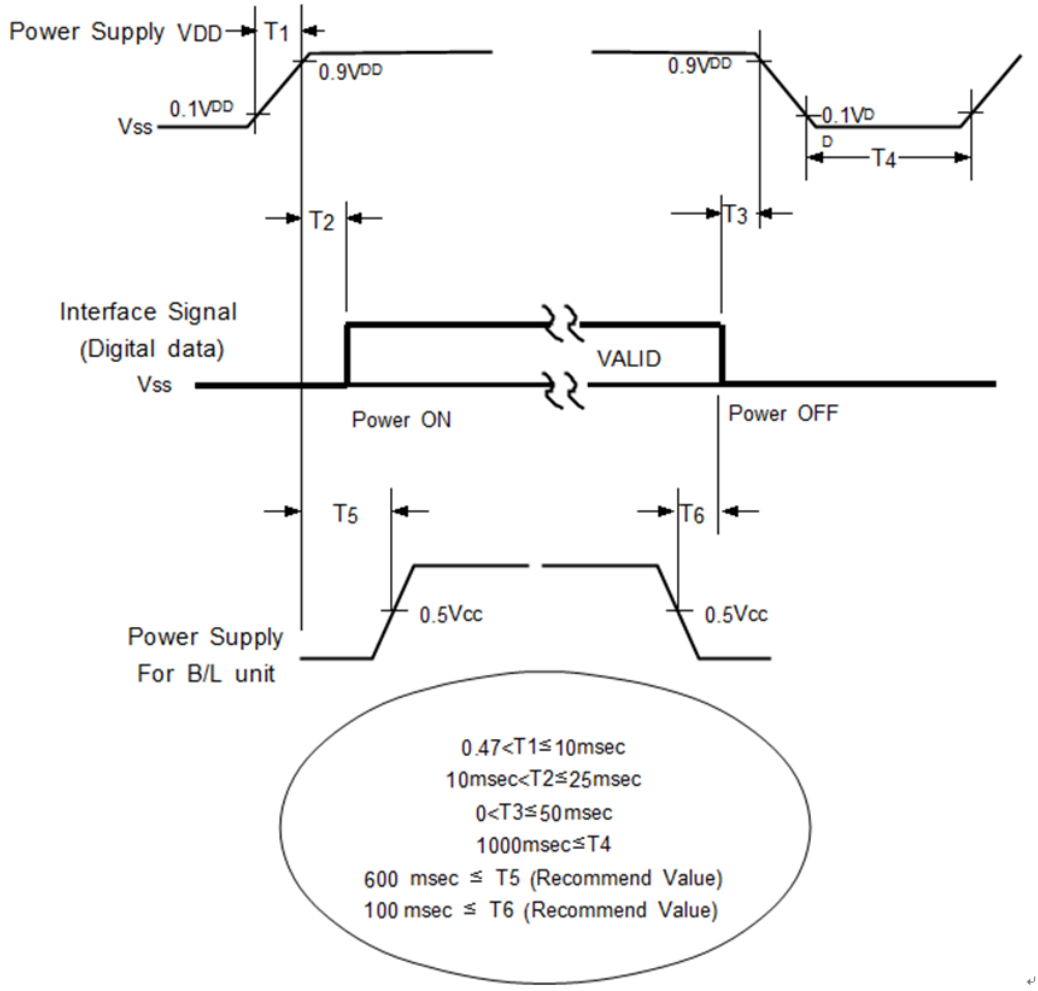
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{DIFF_LVDS}	LVDS differential input	V_{CM_LVDS}=1.2V	100		600	mV
V_{CM_LVDS}	Input common level		VSSL +0.6	1.2	VDDL -0.6	V
F_{CLK}	Input clock frequency		55	75	85	MHz
$\lvert T_{SKEW_LVDS} \rvert$	Clock data skew margin	F_{CLK}=85MHz			400	pS



< Fig 10.1.1 > AC characteristic of LVDS

6.4 The sequence of power on and off

To prevent a latch-up phenomena or the DC operation of the LCD Module, the power on/off sequence should be accorded with the settings described in the diagram below.



- The supply voltage of the external system for the Module input should be the same as the definition of V_{DD}.
- Apply the lamp voltage within the LCD operation range. When the back light turns on before the LCD operation or the LCD turns off before the back light turns off, the display may momentarily show abnormal screen.
- In case of V_{DD} = off level, please keep the level of input signals low or keep a high impedance.
- T4 should be measured after the Module has been fully discharged between power off and on period.
- Interface signal should not be kept at high impedance when the power is on.
- While the V_{DD} is off level, please keep the level of input signals low or keep a high impedance condition.
- The figure of T4 should be measured after the module has been fully discharged between the periods when the power is on and off.

6.5 Input spread spectrum specification

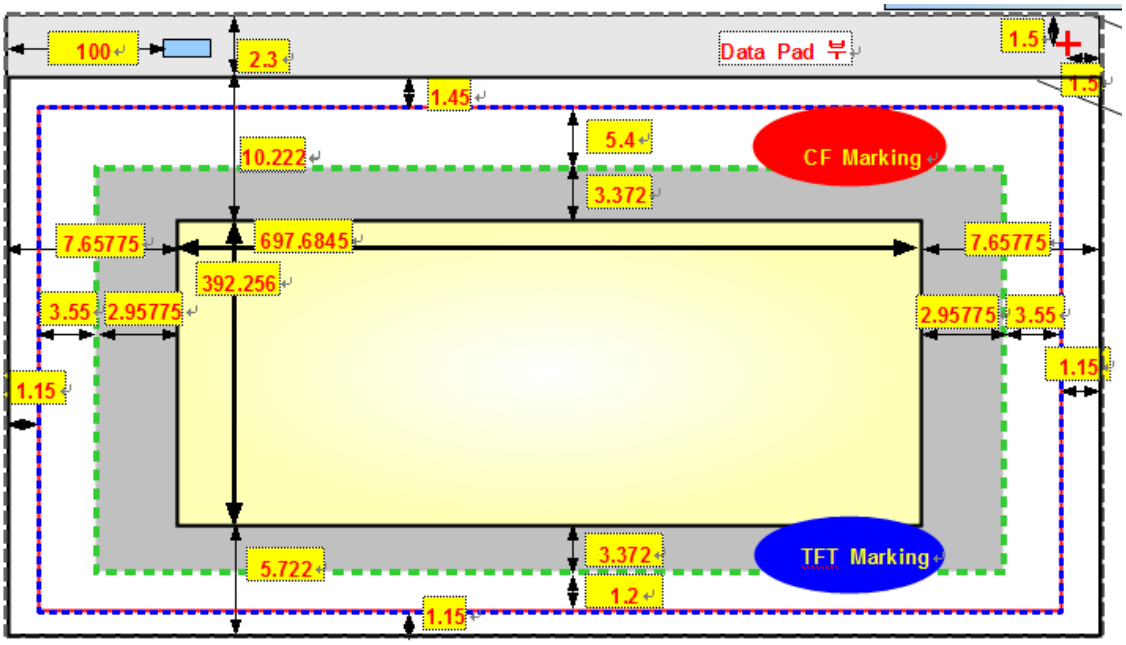
	Modulation Ratio (Max)	Modulation Frequency (Min.)	Modulation Frequency (Max.)
Input Signal	±1.5%	30KHz	150KHz

*SET Vender should check waterfall before apply spread spectrum which occurs based on modulation frequency.

7. Outline dimension

7.1 The adhesive size of POL

The next figure shows the size of POL on the drawing sheet attached to the panel for BLU design.



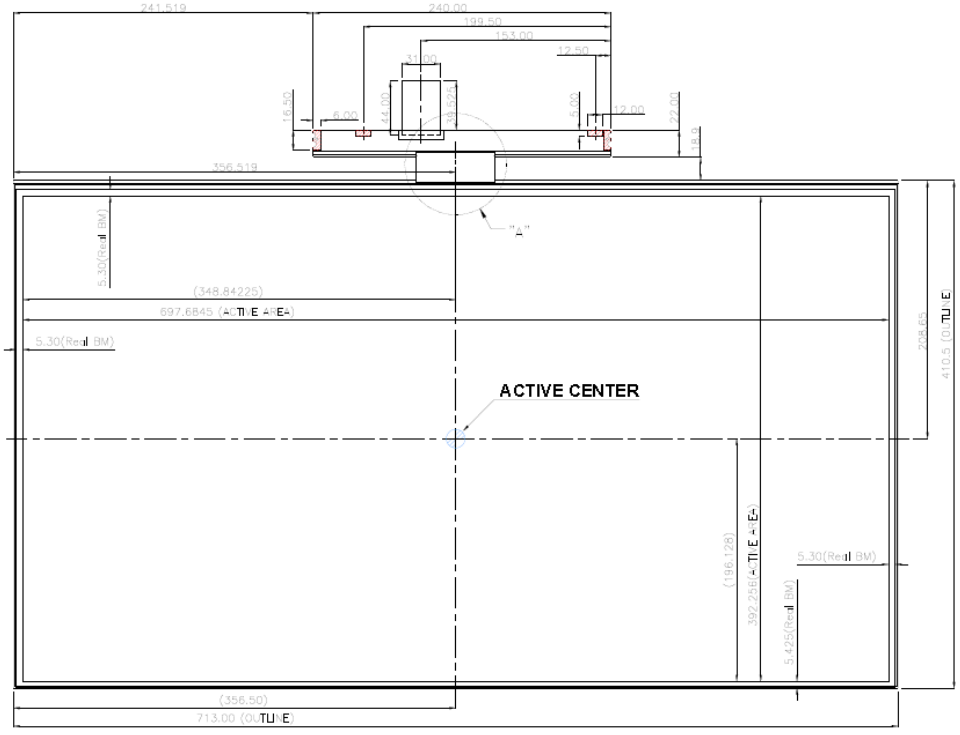
<Figure.>

The POL size of CF : 710.7 X 405.6 mm LEFT&RIGHT ± 0.5mm,

The POL size of TFT: 710.7 X 405.6 mm LEFT&RIGHT ± 0.5mm,

The total adhesion allowance of POL is ± 1.15mm

7.2 The drawing sheet for the size of the OLB bonding



8. Reliability test

8.1 Panel

<table>
<tr><th>Item</th><th>Test Condition</th><th>Quantity</th><th>Note</th></tr>
<tr><td>HTOL</td><td>60 ℃ (Panel change 500hr / circuit change 250hr)</td><td>8</td><td></td></tr>
<tr><td>LTOL</td><td>-5 ℃ (Panel change 500hr / circuit change 250hr)</td><td>4</td><td></td></tr>
<tr><td>THB</td><td>50 ℃ / 90 %RH(Panel change 500hr / circuit change 250hr)</td><td>10</td><td></td></tr>
<tr><td>ASG
Low
temperature</td><td>Max. frequency 25℃~-40℃</td><td>Each
Cell</td><td>ASG Product Only</td></tr>
<tr><td>ASG
High
Temperature</td><td>Min. frequency 60℃Coperation 96hr</td><td>Each
Cell</td><td>ASG Product Only</td></tr>
<tr><td rowspan="2">Image sticking</td><td>25 ℃ / Mosaic pattern(9*10) 12hrs</td><td rowspan="2">8</td><td rowspan="2"></td></tr>
<tr><td>Rolling pattern 12hrs / 3cycles</td></tr>
<tr><td>Decompressio
n</td><td>-40~50℃, 0m(0ft) ~ 13,700m(45,000ft), 72.5Hr</td><td>4</td><td></td></tr>
<tr><td>HTS</td><td>70 ℃, Storage (Panel change 500hr / circuit change 250hr)</td><td>4</td><td></td></tr>
<tr><td>LTS</td><td>-25 ℃, Storage(Panel change 500hr / circuit change 250hr)</td><td>4</td><td></td></tr>
<tr><td>Transportation
condition</td><td>drop(20cm) → temperature/humidity(-30~60℃ / 40℃ 90%RH)
→ pressure → vibration(5~200Hz 1.05Grms, 2hr) → drop(20cm)</td><td>1pallet</td><td></td></tr>
<tr><td>WHTS</td><td>60 ℃ / 75 %RH , Storage ,500HR</td><td>4</td><td></td></tr>
<tr><td>Noise</td><td>Electromagnetic noise: Overall 23dB 이하</td><td>2</td><td></td></tr>
<tr><td>Complex
stress</td><td>-20℃~60℃, 0~90%RH, 2cycle</td><td>4</td><td></td></tr>
<tr><td>ESD</td><td>S-IC Input ±7KV, Output ±4KV</td><td>3</td><td></td></tr>
<tr><td>EOS (optional)</td><td><table><tr><th>Item</th><th>Test condition</th></tr><tr><td>Vin Input step</td><td>Surge combination (High impedance)
Pass Condition: 5kV under</td></tr><tr><td>Signal Input step</td><td>Surge combination (High impedance)
Pass Condition: 120V under</td></tr></table></td><td>2</td><td></td></tr>
</table>

[Criteria on evaluation]

There should be no change of the product, which may affect to the practical display functions, when the display quality test is executed under the normal operation setting.

* HTOL/ LTOL : The operating cycle on the high and low temperature
* THB : Temperature humidity slant
* HTS/LTS : The storage at the high and low temperature
* WHTS : The storage in the high temperature with the high humidity

9. General precautions

9.1 Handling

(a) When the panel kit and BLU kit are assembled, the panel kit and BLU kit should be attached to the set system firmly by combining each mounted holes. Be careful not to give the mechanical stress.

(b) Be careful not to give any extra mechanical stress to the panel when designing the set, and BLU kit.

(c) Be cautious not to give any strong mechanical shock and / or any forces to the panel kit.
Applying the any forces to the panel may cause the abnormal operation or the damage to the panel kit and the back light unit kit.

(d) Refrain from applying any forces to the source PBA and the drive IC in the process of the handling or installing to the set. If any forces are applied to the products, it may cause damage or a malfunction in the panel kit.

(e) Refrain from applying any forces which cause a constant shock to the back side of panel kit, the set design and BLU kit. If any forces are applied to the products, it may cause an abnormal display, a functional failure and etc.

(f) Note that polarizer could be damaged easily.
Do not press or scratch the bare surface with the material which is harder than a HB pencil lead.

(g) Wipe off water droplets or oil immediately. If you leave the droplets for a long time on the product, a staining or the discoloration may occur.

(h) If the surface of the polarizer is dirty, clean it using the absorbent cotton or the soft cloth.

(i) Desirable cleaners are water or IPA (Isopropyl Alcohol).
Do not use Kenton type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. These might cause the permanent damage to the polarizer due to chemical reaction.

(j) If the liquid crystal material leaks from the panel, this should be kept away from the eyes or mouth. If this contacts to hands, legs, or clothes, you must washed it away with soap thoroughly and see a doctor for the medical examination.

(k) Protect the panel kit and BLU Kit out of the static electricity. Otherwise the circuit IC could be damaged.

- Reference : Process control standard of SDC

No.	Item	Control standard
1	Ionizer	All Equipment should be controlled under 150V.(Typ. 100V)
2	Carrying Roller	Carrying Roller should be controlled under 200V.
3	Equipment Ground Resistance	All Equipment Ground Should be less than 1ohm.

(l) Remove the stains with finger-stalls wearing soft gloves in order to keep the display clean in the process of the incoming inspection and the assembly process.

(m) Do not pull or fold the source drive IC which connects to the source PBA and the panel or the gate drive IC.

(n) Do not pull, fold or bend the source drive IC and the gate drive IC in any processes.
If not, the source drive IC could be bent one time in the process of assembling the panel Kit and the BLU Kit.

(o) Do not adjust the variable resistor located on the panel kit and BLU kit except when adjusting the flicker.

(p) Do not touch the pins of the interface connector directly with bare hands.

(q) Be cautious not to be peeled off the protection film.

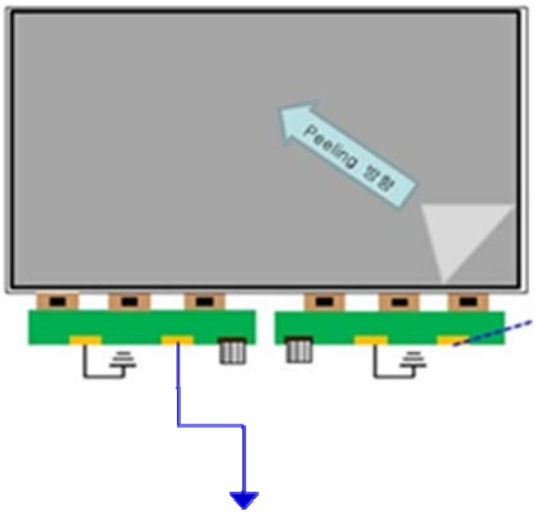


Fig. GND SR-Open Pattern – Be sure to be contacted to the ground while peeling of the protection film

- Make sure to peel off slowly
(It is recommended to peel it off at the speed of more than 8sec. constantly.)
- The peeling direction is shown at the Fig
- Instruct the ground worker to work with the adequate methods such as the antistatic wrist band.
- Maker sure to be grounded the source PBA while peeling of the protection film.
- Ionized air should be blown over during the peeling
- The protection film should not t be contacted to the source drive IC.
- If the adhesive stains remain on the polarizer after the protection film is peeled off, please move stains with isopropyl-alcohol liquid.

(r) The protection film for the polarizer on the panel kit should be slowly peeled off just before using so that the electrostatic charge can be minimized.

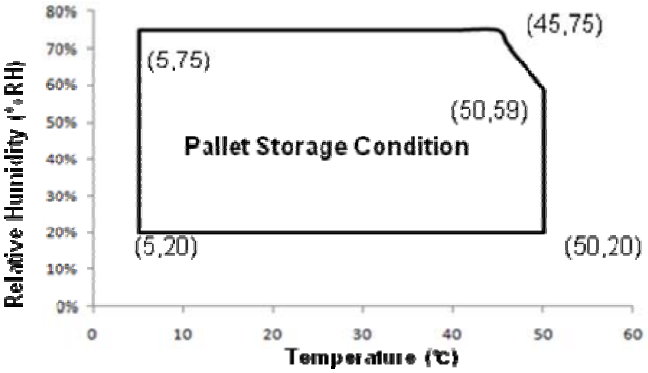
(s) The panel kit and BLU kit have high frequency circuits. The sufficient suppression to the EMI should be done by the set manufacturers.

(t) The set of which the panel is assembled shall not be twisted. If the product is twisted, it may cause the damage on the product.

(u) Surface Temp. of IC should be controlled less than 100℃, operating over the Temp. can cause the damage or decrease of lifetime.

9.2 Storage

The storage condition for packing (Not included transportation)

<table>
<tr><th>ITEM</th><th>Unit</th><th colspan="5">Min.</th><th>Max.</th></tr>
<tr><td>Storage Temperature</td><td>(℃)</td><td colspan="6" rowspan="2"> 
</td></tr>
<tr><td>Storage Humidity</td><td>(%rH)</td></tr>
<tr><td>Storage life</td><td colspan="7">6 months</td></tr>
<tr><td>Storage Condition</td><td colspan="7">(1) The storage room should provide good ventilation and temperature control.
(2) Products should not be placed on the floor, but on the Pallet away from a wall.
(3) Prevent products from direct sunlight, moisture nor water; Be cautious of a buildup of condensation.
(4) Avoid other hazardous environment while storing goods.
(5) If products delivered or kept in conditions of the recommended temperature or humidity, we recommend you leave them at a circumstance which is shown in the following table.</td></tr>
<tr><td></td><td>period</td><td>1 month</td><td>2 months</td><td>3 months</td><td>4 months</td><td>5 months</td><td>6 months</td></tr>
<tr><td></td><td>Baking Condition</td><td colspan="2">No Baking</td><td>50℃, 10% 24Hr</td><td colspan="3">50℃, 10%, 48Hr</td></tr>
</table>

9.3 Operation

(a) Do not connect or disconnect the FFC cable during the "Power On" condition.

(b) Power supply should be always turned on and off by the "Power on/off sequence"

(c) The module has high frequency circuits. The sufficient suppression to the electromagnetic interference should be done by the system manufacturers. The grounding and shielding methods is important to minimize the interference.

(d) The cables between TV SET connector and Control PBA interface cable should be connected directly to have a minimized length. A longer cable between TV SET connector and Control PBA interface cable maybe operate abnormal display

(e) Recommend to age for over 1 hour at least in the state, which the product is driving initially to stabilize the characteristic of the initial TFT.

(f) Response time depends on the temperature.(In Lower temperature, it becomes longer)

9.4 Operation condition guide

(a) The LCD product shall be operated under normal conditions.
The normal condition is defined as below;
- Temperature : 20±15℃
- Humidity : 55±20%
- Display pattern : continually changing pattern (Not stationary)

(b) If the product will be used under extreme conditions such as under the high temperature, humidity, display patterns or the operation time etc.., it is strongly recommended to contact SDC for the advice about the application of engineering . Otherwise, its reliability and the function may not be guaranteed. Extreme conditions are commonly found at airports, transit stations, banks, stock markets, and controlling systems.

9.5 Others

(a) The ultra-violet ray filter is necessary for the outdoor operation.

(b) Avoid the condensation of water which may result in the improper operation of product or the disconnection of electrode.

(c) Do not exceed the limit on the absolute maximum rating. (For example, the supply voltage variation, the input voltage variation, the variation in content of parts and environmental temperature, and so on) If not, panel may be damaged.

(d) If the module keeps displaying the same pattern for a long period of time, the image may be remained to the screen. To avoid the image sticking, it is recommended to use a screen saver.

(e) This Panel has its circuitry of PCB's on the rear side, so it should be handled carefully in order for a force not to be applied.

(f) Please contact the SDC in advance when the same pattern is displayed for a long time

10. Special precautions

10.1 Lists to be cautious when executing the design process

No.	Component	Expected cause
1	Upholding part for panel	Prevent the panel from breaking by assigning gaps between the panel and the upholding part for panel on the drawing for the upholding part for panel. Refer to the (a), (b), (c) of 3-1 for the design of BLU.
2	The shape of the upholding part for panel	Design the upholding part for panel to fit to the panel appropriately when designing the BLU since the shape of the upholding part for panel may damage the panel. Refer to the (a), (b), (c) of 3-1 for the design of BLU.
3	The edge of upholding part for panel	Design the edge of panel to have a sufficient space with the upholding part for panel when designing the BLU since the edge of the upholding part for panel may damage the panel when assembling the panel and BLU. Refer to the (a), (b), (c) of 3-1 for the design of BLU.
4	Upholding part for panel	Place the upholding part for the panel in order for the shape of mold, which contacts with the panel not to interfere with the area of panel. Refer to the (a), (b), (c) of 3-1 for the design of BLU.
5	Drive IC	Design the BLU in order for the COF not to contain the lead crack resulted from the tensioned COF created when the product is twisted if the space between the D-IC COF and the middle mold isn't sufficient. Refer to the (a), (b), (c),(d),(e),(f), and (g)of 3-2 for the design of BLU.
6	Drive IC	Design the BLU in order for the product not to contain the lead crack resulted from the tensioned COF caused under the condition, which the product is twisted by fixing the source PCB. Refer to the (a), (b), (c),(d),(e),(f), and (g)of 3-2 for the design of BLU.
7	IC component	1) The temperature of each part of product suggested by our company and the second vendor shall meet the standard of temperature, which is recommended not to be exceeded by our company when the product is affected under the various temperature ranges. Apply over 1mm long separation distance stated in the safety standard between the electric part and each conductor. (Apply the rated separation distance when insulating.)
8	Thermal pad	Apply the thermal pad in a designated size to the product as a measure to lower the temperature of heat in order for each part to use the rated temperature.
9	POL	The surrounding area of the POL shall be treated with an electrification treatment since the external ESD may cause a phenomenon, which the POL is coming off. In addition, the GND portion of source PBA shall be grounded.
10	PBA	The GND portion of each PBA shall be contacted with the GND portion of BLU. Refer to the (a) and (b) of 3-3 for the design of BLU.
11	Circuit	The standardized approval from the client is required since the EMI is executed by a client. Our company can only measure the reference since the client measures the BLU.
12	The height of component	Design the BLU with considering the maximum height of parts, which our company suggests.
13	Between the FFC and the C-PBA	Design the instrument with considering the length between the FFC and the control PBA. (The marginal minimum length of 5mm or 8mm is required.)
14	Panel	The surface temperature of panel shall be maintained within 0℃ and 45℃ when the external ambient temperature is at 25℃. (Design the BLU with considering the increase of the temperature in the panel by the LED, CCFL, and etc.)
15	Aging	Recommend to age for over 1 hour at least in the state, which the product is driving initially to stabilize the characteristic of the initial TFT.
16	The attachment of gasket	The additional confirmation by our company is required If the attachment of gasket to the S-PBA of our company is required.(To fix the S-PBA or the EMI)
17	Drive IC	Design the top chassis and the driver IC to be contacted by placing the shape of emboss inside the top chassis as a measure to prevent the driver IC from heating. The size of emboss shall be designed in larger size than the size of IC inside the film of the driver IC. Refer to the (a), (b), (c),(d),(e),(f), and (g)of 3-2 for the design of BLU.
18	The prohibited bandwidth	Design the BLU in order for the BLU not to interfere with the area, where the control PBA and the source PBA are located densely according to the drawing for the BLU from our company.
19	S-PBA	The material, which contacts with the bottom side of S-PBA which has a pattern shall be non-conducting material or shall be insulated.

11. EDID Information

11.1 EEPROM Data Format

EEPROM Data					
No	Item	Spec	Address	Data	Remark
1	Panel Product Vender	HDLCD	000	00	SONY Choice - Note 1
2	Screen Size	32	001	20	16 Hexadecimal
3	H-Resolution	1366	002,003	05,56	16 Hexadecimal
4	V-Resolution	768	004,005	03,00	16 Hexadecimal
5	Vertical Frequency	50/60Hz	006	00	- Note 2
6	Data Format	8bit	007	01	- Note 3
7	FRC Revision Information	1st	0ED	00	ASCII - Note 4
8	Part Number	LSY320AN 0210	0E0~0EB	4C,53,59,33,32,30, 41,4E,30,32,31,30	ASCII - Note 5, 6

Note1)

Data	Panel Vender Code
00	HDLCD(SEC)
01	Others
02	Others
03	Others
04	Others
05	Others

Note2)

Data	V-Frequency
00	50/60Hz
01	100/120HZ
02	200/240Hz

Note3)

Data	Data Format
00	6Bit
01	8Bit
02	10Bit

Note4) FRC Revision Code will be Changed from “00” to “41” (A) When FRC IC is changed.
At First MP. This Code will be “00”

Note 5) LSY[Z]XXXXXXX Only for SDC Model

Note 6) Rest of them must be “00” (Null)

11.2 EEPROM Data Table

	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
0	**00**	**20**	**05**	**56**	**03**	**00**	**00**	**01**	00	00	00	00	00	00	00	00
1	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
2	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
3	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
4	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
5	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
6	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
7	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
8	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
9	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
A	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
B	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
C	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
D	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00
E	**4C**	**53**	**59**	**33**	**32**	**30**	**41**	**4E**	**30**	**32**	**31**	**30**	00	00	00	00
F	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00	00

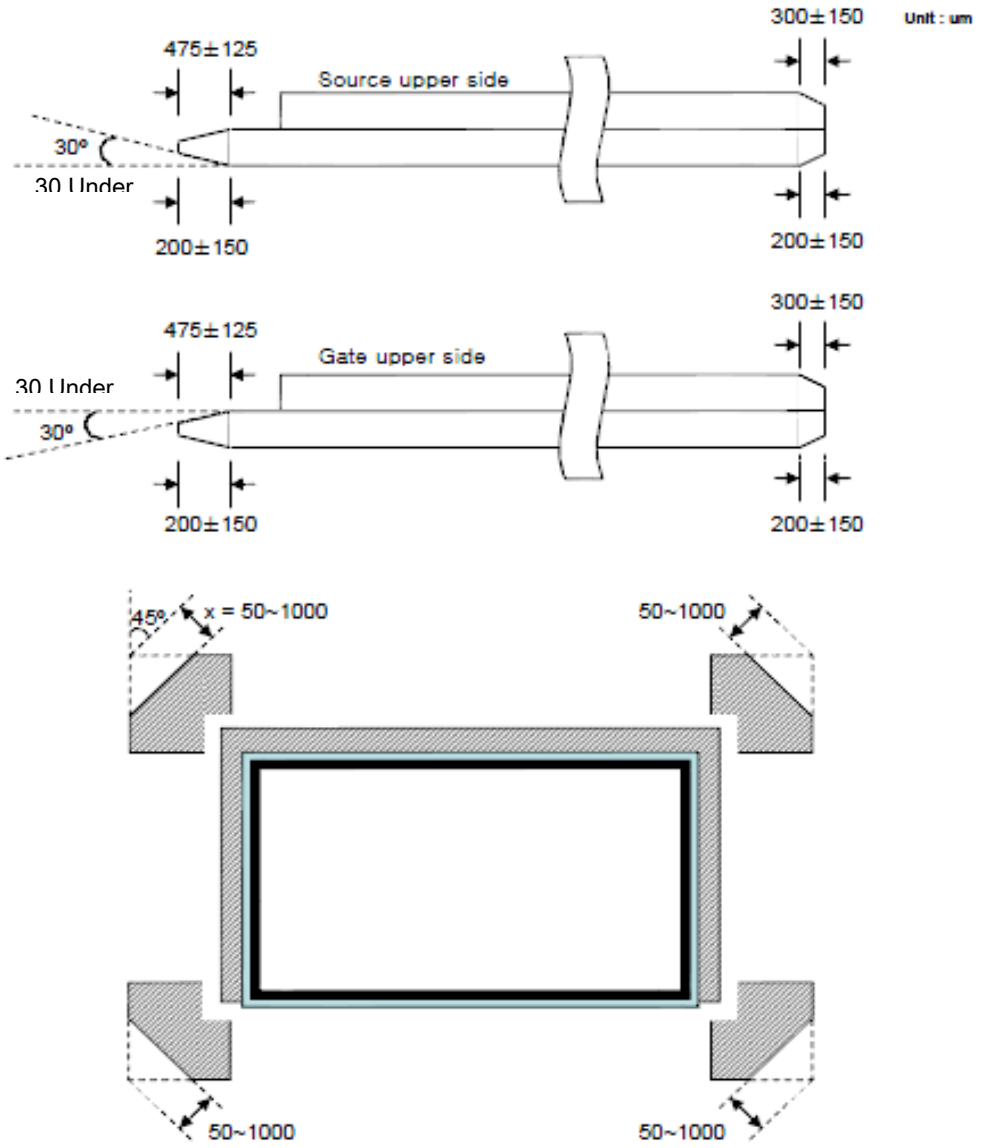
Note) EDID Data are written in Sub address 0000h ~ 00FFh.

Other area (Sub address 0100h ~ 0FFFh) of EEPROM data are managed by Sony.

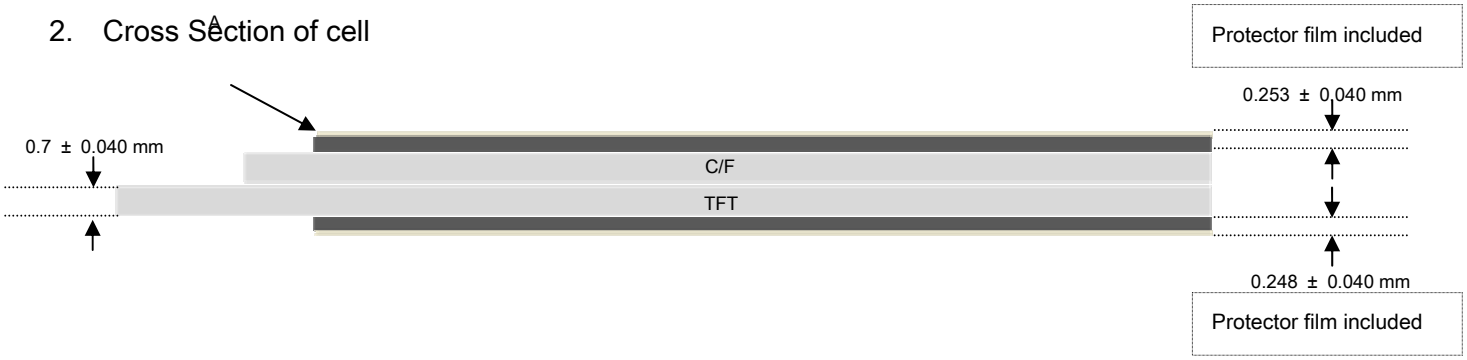
Appendix1

Reference of each Panel size

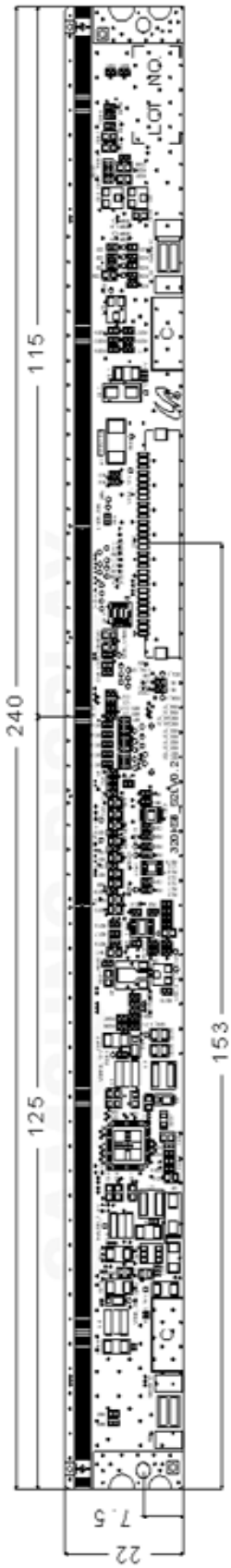
1. Amount of beveling of panel



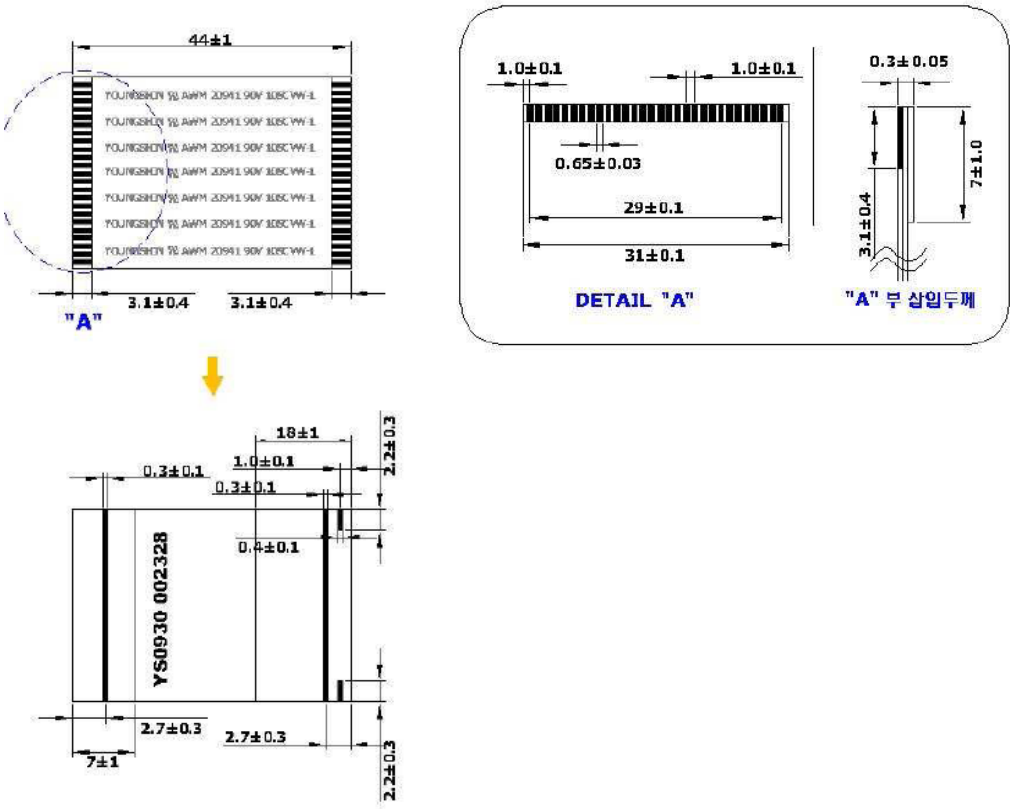
2. Cross Section of cell



3. Source PCB



4. FFC Cable


44±1
3.1±0.4
3.1±0.4
"A"
1.0±0.1
1.0±0.1
0.65±0.03
29±0.1
31±0.1
DETAIL "A"
0.3±0.05
7±1.0
3.1±0.4
"A" 부 상입두께
18±1
0.3±0.1
1.0±0.1
0.3±0.1
2.2±0.3
0.4±0.1
YS0930 002328
2.7±0.3
2.7±0.3
7±1
2.2±0.3

Appendix2

Spectrum Data of SONY BLU

(LTY320AN05-A)

1. Spectrum Data of SONY BLU (LTY320AN05-A)

WL(nm)	Watts/sr/msr	WL(nm)	Watts/sr/msr	WL(nm)	Watts/sr/msr	WL(nm)	Watts/sr/msr	WL(nm)	Watts/sr/msr
380	6.12E-03	430	1.20E-01	480	2.07E-02	530	1.18E-01	580	8.24E-02
381	6.62E-03	431	1.38E-01	481	1.90E-02	531	1.20E-01	581	8.17E-02
382	6.05E-03	432	1.60E-01	482	1.76E-02	532	1.22E-01	582	8.12E-02
383	6.05E-03	433	1.81E-01	483	1.63E-02	533	1.23E-01	583	8.05E-02
384	5.51E-03	434	2.07E-01	484	1.52E-02	534	1.24E-01	584	8.02E-02
385	5.44E-03	435	2.33E-01	485	1.42E-02	535	1.26E-01	585	7.97E-02
386	4.65E-03	436	2.61E-01	486	1.35E-02	536	1.27E-01	586	7.92E-02
387	4.21E-03	437	2.91E-01	487	1.30E-02	537	1.28E-01	587	7.86E-02
388	3.78E-03	438	3.25E-01	488	1.26E-02	538	1.28E-01	588	7.82E-02
389	3.72E-03	439	3.56E-01	489	1.23E-02	539	1.29E-01	589	7.80E-02
390	3.14E-03	440	3.85E-01	490	1.21E-02	540	1.29E-01	590	7.78E-02
391	2.79E-03	441	4.14E-01	491	1.21E-02	541	1.29E-01	591	7.77E-02
392	2.54E-03	442	4.33E-01	492	1.23E-02	542	1.29E-01	592	7.72E-02
393	2.34E-03	443	4.53E-01	493	1.26E-02	543	1.28E-01	593	7.71E-02
394	2.20E-03	444	4.61E-01	494	1.31E-02	544	1.28E-01	594	7.70E-02
395	1.96E-03	445	4.58E-01	495	1.36E-02	545	1.27E-01	595	7.69E-02
396	1.82E-03	446	4.50E-01	496	1.44E-02	546	1.26E-01	596	7.64E-02
397	1.73E-03	447	4.36E-01	497	1.54E-02	547	1.25E-01	597	7.65E-02
398	1.58E-03	448	4.14E-01	498	1.64E-02	548	1.24E-01	598	7.63E-02
399	1.54E-03	449	3.87E-01	499	1.78E-02	549	1.22E-01	599	7.61E-02
400	1.49E-03	450	3.57E-01	500	1.93E-02	550	1.21E-01	600	7.60E-02
401	1.53E-03	451	3.29E-01	501	2.09E-02	551	1.20E-01	601	7.59E-02
402	1.48E-03	452	2.98E-01	502	2.28E-02	552	1.19E-01	602	7.58E-02
403	1.58E-03	453	2.70E-01	503	2.48E-02	553	1.17E-01	603	7.54E-02
404	1.64E-03	454	2.47E-01	504	2.69E-02	554	1.16E-01	604	7.54E-02
405	1.82E-03	455	2.22E-01	505	2.95E-02	555	1.14E-01	605	7.53E-02
406	2.01E-03	456	2.03E-01	506	3.21E-02	556	1.13E-01	606	7.49E-02
407	2.35E-03	457	1.85E-01	507	3.50E-02	557	1.11E-01	607	7.48E-02
408	2.58E-03	458	1.69E-01	508	3.82E-02	558	1.09E-01	608	7.45E-02
409	2.99E-03	459	1.55E-01	509	4.14E-02	559	1.08E-01	609	7.41E-02
410	3.57E-03	460	1.42E-01	510	4.48E-02	560	1.06E-01	610	7.41E-02
411	4.28E-03	461	1.29E-01	511	4.83E-02	561	1.04E-01	611	7.36E-02
412	5.01E-03	462	1.18E-01	512	5.21E-02	562	1.03E-01	612	7.33E-02
413	6.03E-03	463	1.07E-01	513	5.61E-02	563	1.02E-01	613	7.31E-02
414	7.26E-03	464	9.61E-02	514	6.01E-02	564	1.00E-01	614	7.26E-02
415	8.72E-03	465	8.64E-02	515	6.42E-02	565	9.87E-02	615	7.23E-02
416	1.06E-02	466	7.78E-02	516	6.81E-02	566	9.73E-02	616	7.19E-02
417	1.28E-02	467	6.97E-02	517	7.21E-02	567	9.60E-02	617	7.15E-02
418	1.56E-02	468	6.28E-02	518	7.57E-02	568	9.45E-02	618	7.11E-02
419	1.89E-02	469	5.66E-02	519	7.97E-02	569	9.32E-02	619	7.05E-02
420	2.27E-02	470	5.09E-02	520	8.36E-02	570	9.19E-02	620	7.03E-02
421	2.72E-02	471	4.62E-02	521	8.74E-02	571	9.07E-02	621	6.97E-02
422	3.28E-02	472	4.18E-02	522	9.12E-02	572	8.94E-02	622	6.92E-02
423	3.90E-02	473	3.81E-02	523	9.50E-02	573	8.83E-02	623	6.87E-02
424	4.65E-02	474	3.49E-02	524	9.85E-02	574	8.74E-02	624	6.84E-02
425	5.47E-02	475	3.20E-02	525	1.02E-01	575	8.64E-02	625	6.78E-02
426	6.48E-02	476	2.92E-02	526	1.06E-01	576	8.56E-02	626	6.73E-02
427	7.62E-02	477	2.67E-02	527	1.10E-01	577	8.48E-02	627	6.69E-02
428	8.94E-02	478	2.45E-02	528	1.13E-01	578	8.39E-02	628	6.62E-02
429	1.03E-01	479	2.26E-02	529	1.16E-01	579	8.31E-02	629	6.56E-02

< 380nm ~ 629nm >

WL(nm)	Watts/sr/msr	WL(nm)	Watts/sr/msr	WL(nm)	Watts/sr/msr	WL(nm)	Watts/sr/msr
630	6.51E-02	680	2.73E-02	730	5.49E-03	780	1.48E-03
631	6.48E-02	681	2.66E-02	731	5.32E-03		
632	6.41E-02	682	2.60E-02	732	5.14E-03		
633	6.35E-02	683	2.53E-02	733	5.02E-03		
634	6.30E-02	684	2.46E-02	734	4.85E-03		
635	6.25E-02	685	2.40E-02	735	4.72E-03		
636	6.20E-02	686	2.34E-02	736	4.57E-03		
637	6.12E-02	687	2.28E-02	737	4.46E-03		
638	6.05E-02	688	2.23E-02	738	4.36E-03		
639	5.98E-02	689	2.17E-02	739	4.24E-03		
640	5.91E-02	690	2.11E-02	740	4.13E-03		
641	5.83E-02	691	2.06E-02	741	4.05E-03		
642	5.74E-02	692	2.00E-02	742	3.97E-03		
643	5.67E-02	693	1.95E-02	743	3.89E-03		
644	5.60E-02	694	1.90E-02	744	3.79E-03		
645	5.51E-02	695	1.85E-02	745	3.72E-03		
646	5.45E-02	696	1.80E-02	746	3.64E-03		
647	5.36E-02	697	1.74E-02	747	3.56E-03		
648	5.28E-02	698	1.68E-02	748	3.49E-03		
649	5.21E-02	699	1.64E-02	749	3.41E-03		
650	5.13E-02	700	1.58E-02	750	3.35E-03		
651	5.04E-02	701	1.54E-02	751	3.29E-03		
652	4.96E-02	702	1.49E-02	752	3.22E-03		
653	4.87E-02	703	1.44E-02	753	3.14E-03		
654	4.79E-02	704	1.40E-02	754	3.06E-03		
655	4.69E-02	705	1.36E-02	755	2.99E-03		
656	4.61E-02	706	1.32E-02	756	2.92E-03		
657	4.53E-02	707	1.28E-02	757	2.86E-03		
658	4.44E-02	708	1.24E-02	758	2.77E-03		
659	4.36E-02	709	1.20E-02	759	2.72E-03		
660	4.28E-02	710	1.16E-02	760	2.65E-03		
661	4.19E-02	711	1.13E-02	761	2.57E-03		
662	4.09E-02	712	1.09E-02	762	2.49E-03		
663	4.01E-02	713	1.05E-02	763	2.45E-03		
664	3.93E-02	714	1.01E-02	764	2.37E-03		
665	3.84E-02	715	9.81E-03	765	2.30E-03		
666	3.76E-02	716	9.46E-03	766	2.22E-03		
667	3.68E-02	717	9.11E-03	767	2.17E-03		
668	3.60E-02	718	8.78E-03	768	2.12E-03		
669	3.52E-02	719	8.47E-03	769	2.06E-03		
670	3.44E-02	720	8.14E-03	770	1.98E-03		
671	3.36E-02	721	7.81E-03	771	1.93E-03		
672	3.29E-02	722	7.53E-03	772	1.89E-03		
673	3.21E-02	723	7.22E-03	773	1.82E-03		
674	3.14E-02	724	6.94E-03	774	1.77E-03		
675	3.07E-02	725	6.66E-03	775	1.71E-03		
676	3.01E-02	726	6.40E-03	776	1.67E-03		
677	2.93E-02	727	6.18E-03	777	1.61E-03		
678	2.86E-02	728	5.95E-03	778	1.57E-03		
679	2.80E-02	729	5.71E-03	779	1.52E-03		

< 630nm ~ 780nm >

Spectrum data

Appendix3

Driver IC ESD Specification

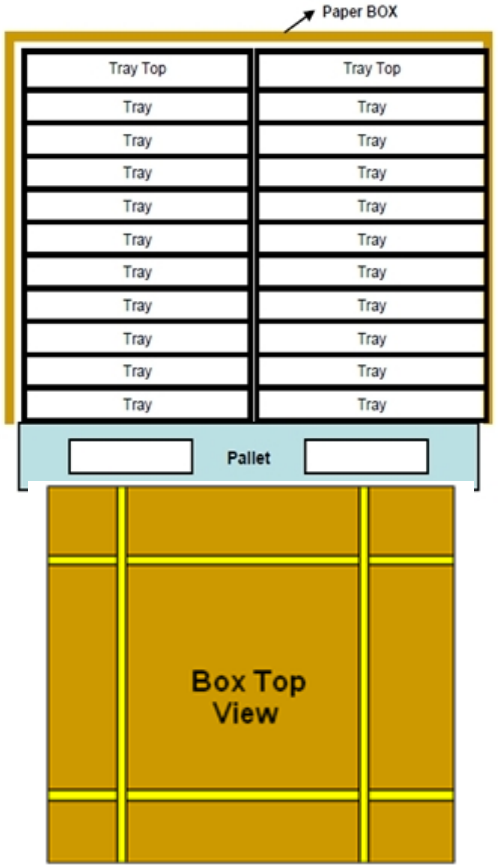
1. D-IC ESD Specification

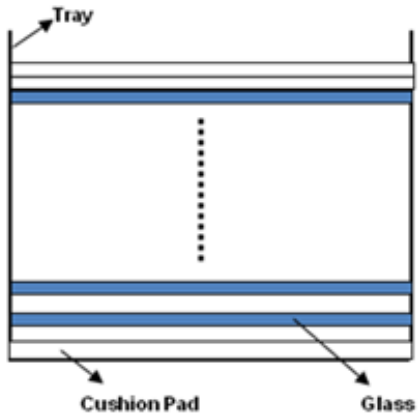
D-IC	FFC PIN INPUT	D-IC Ouput
DB7501	±7kV	±4kV

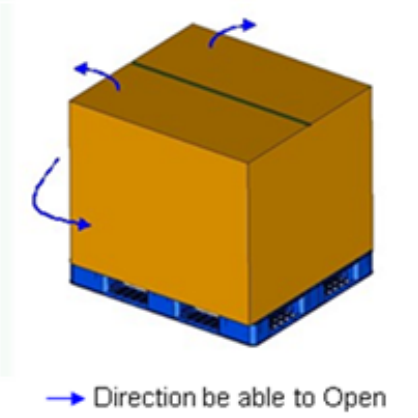
Appendix4

Packing Information

1. Panel Kit Packing







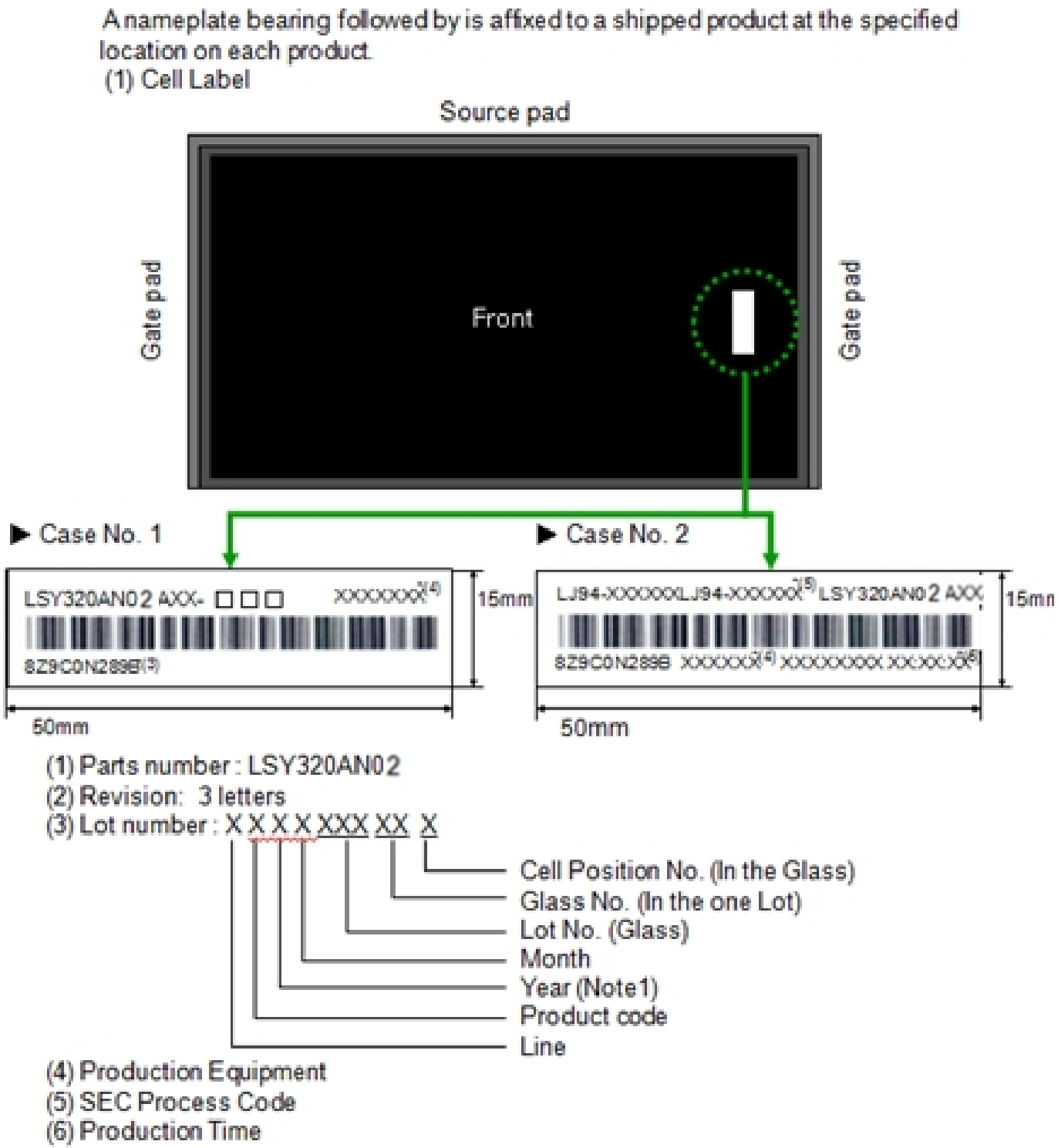
Item	Dimension	Weight	Q'ty / PLT	Total Weight
	W x L x H (mm)	g	pcs	Kg
Packing Tray	894 x 634 x 112	968	20	292.4
Pallet	1150 x 1270 x 125	18080	1	
Panel	-	1200	200	
Tray Top	894 x 634 x 40	620	2	
Cushion Pad	717 x 452.3 x 2.5	26	220	
Silica gel	-	40	80	
Paper Box	908 x 1282 x 1045	4845	1	
Stack Layer	max	2	Pallet	
Total Size	1150 x 1282 x 1170			-

NOTE) The Cushion PAD is worked out for antistatic device.

2. Panel Kit Marking & Others

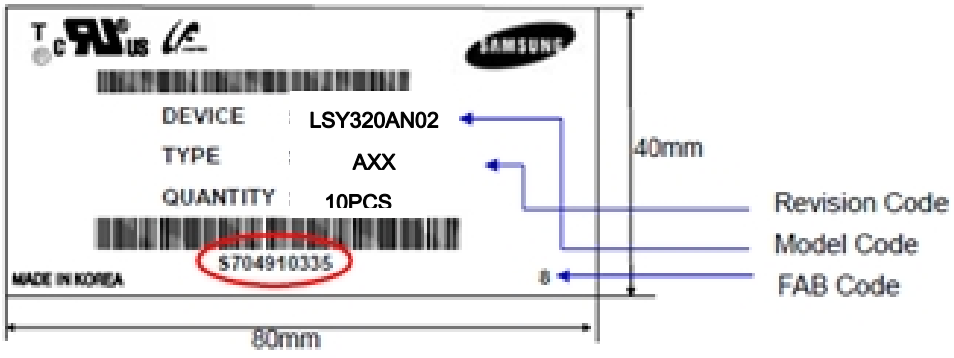
A nameplate bearing followed by is affixed to a shipped product at the specified location on each product.

(1) Cell Label

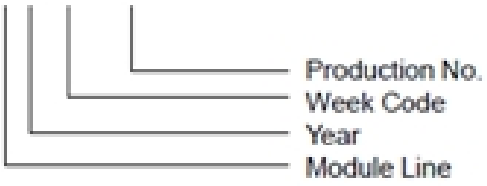


(2) Tray Label

(2) Tray Label



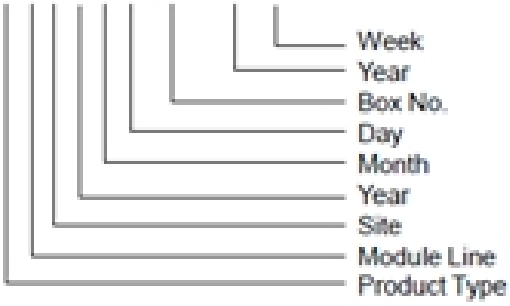
※ Lot number : S X X XX XXXXX



(3) Box Label

(3) BOX Label

BOX Serial : X X X X X X XXXX XX XX



Appendix5

Mechanical Information

1. Mechanical Information

Item		Specification			unit	Notes
		Min	Typ	Max		
Cell size (TFT glass)	H	-	713.0	-	mm	
	V	-	410.5	-		
	T	660	700	740	μm	
Cell size (CF glass)	H	-	713.0	-	mm	
	V	-	408.2	-		
	T	660	700	740	μm	
Polarizer size (TFT side)	H	710.20	710.70	711.20	mm	
	V	405.10	405.60	406.10		
	T	208	248	288	μm	
Polarizer size (CF side)	H	710.20	710.70	711.20	mm	
	V	405.10	405.60	406.10		
	T	213	253	293	μm	
Surface hardness of polarizer			2H	-	-	
Warp of Cell Ass'y		-1		+1	mm	(1)

Note (1) Measurement Method

a. Measurement Timing : After OLB Process at SDC Line

b. Measure a gap on surface plate by using thickness gauge.

Measure 4point(a,b,c,d) as Fig 1.

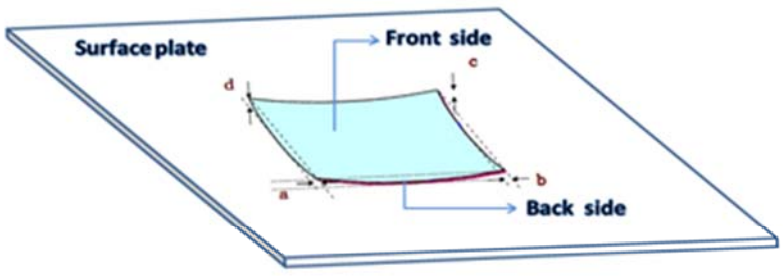


Fig 1

Appendix6

Caution

(1) When using BLU PWM(Pulse Width Modulation), PWM frequency is recommended to be 1.5 times of Frame Frequency(Fv) for preventing waterfall phenomenon.

(2) SDC recommends that operating time as open-cell should not over 10min and during operating, D-IC's Tj shouldn't be over 125℃.